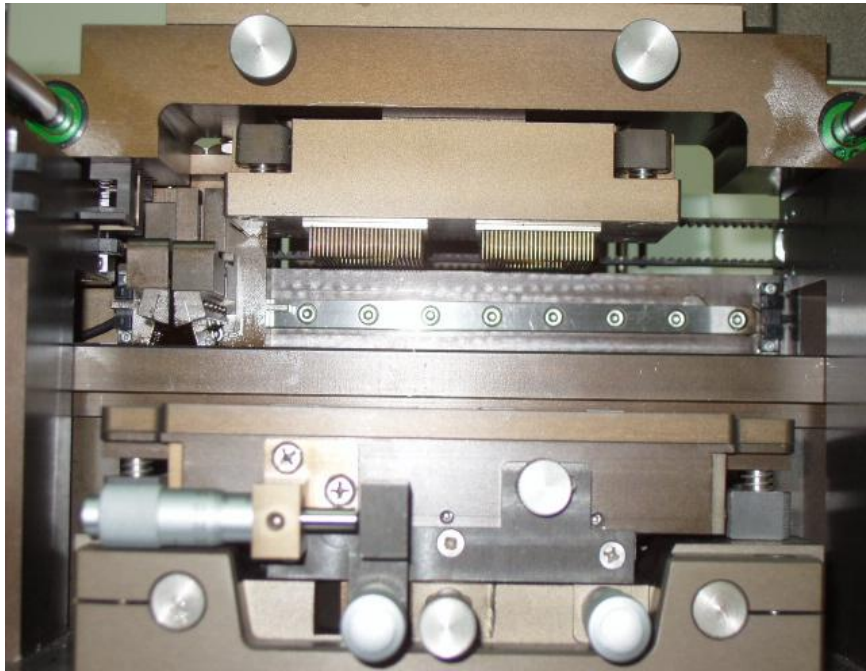


移印锡球植入机 BU-570

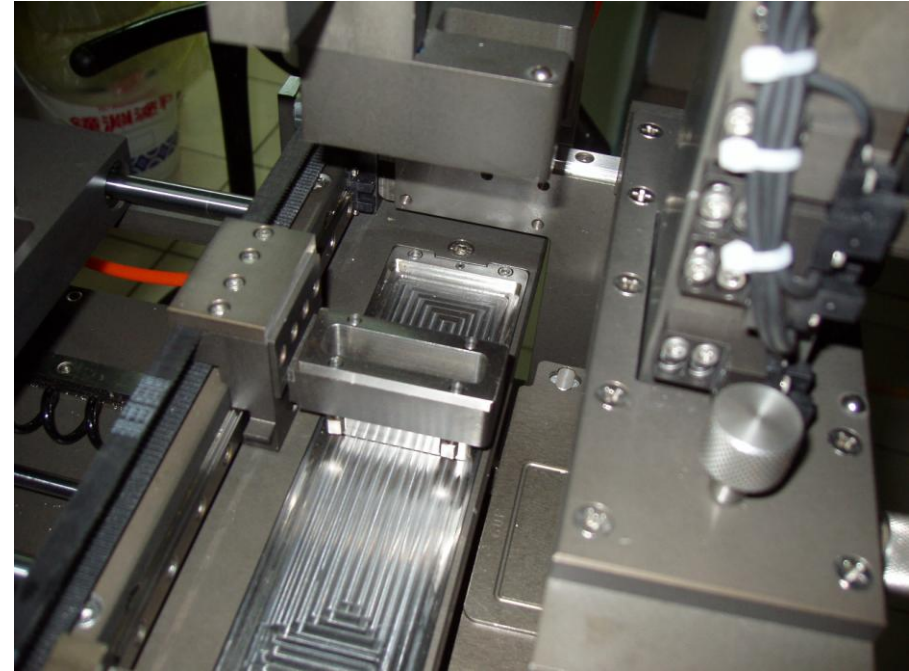
植球能力: $0.35\Phi\sim0.76\Phi$ 植球范围:L-60mm. W-80mm



移印 pin 针座

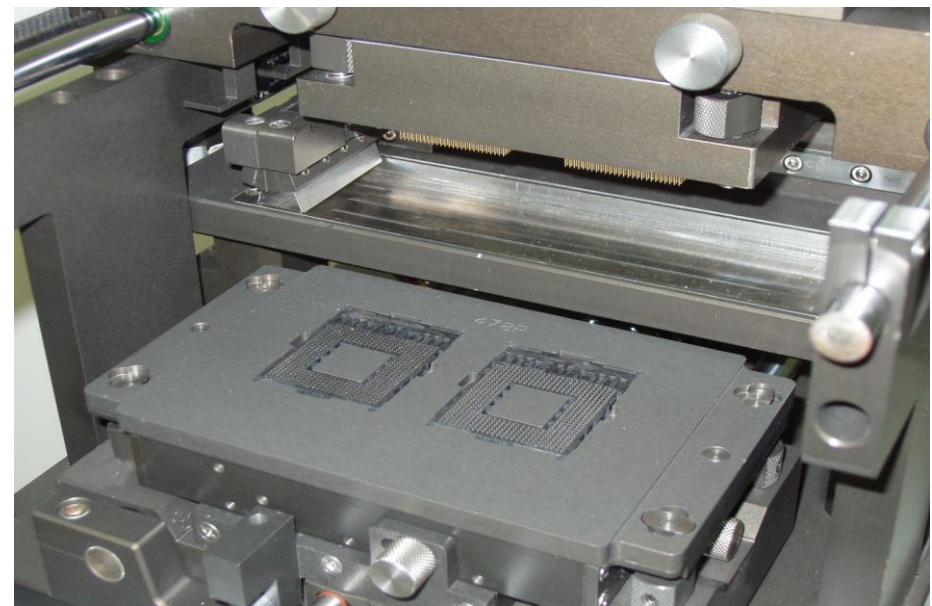


移印刮刀



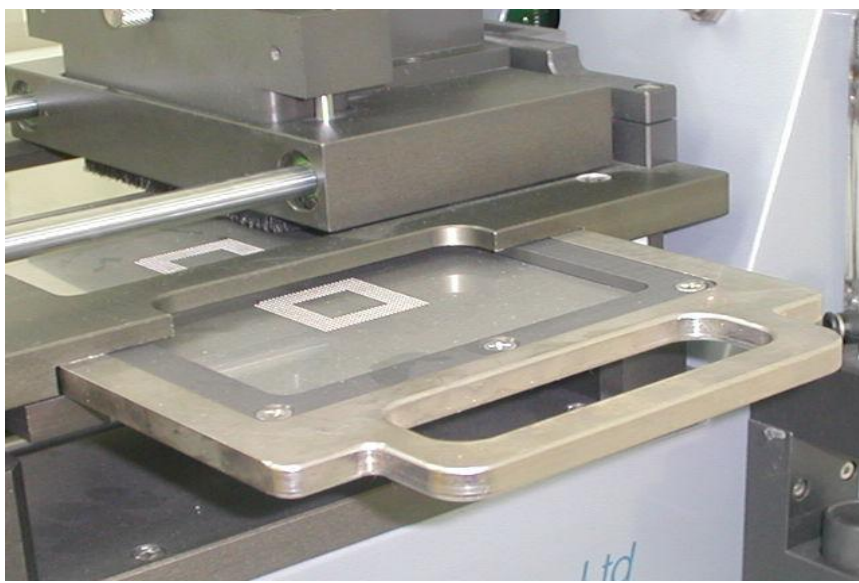
触控面板-提供功能与数据条件设定

X. Y. θ . 分厘卡调整滑座与脚座模具



卡夹抽取式锡球模具更换座

除球收集瓶座(清球配置)



BGA **再造**

BGA **regeneration!**

~以低廉锡球,重新植入再造完整 BGA~

~ Place solder balls on BGA to regenerate a whole new one with the lowest cost. ~

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移印锡球植入机

BGA rework equipment --- Solder ball placement system BU-570

- (1) 外部尺寸: 84cm(L),X 36cm(W),X 59cm(H)
■ **Outside dimension: 84cm(L), 36cm(W), 59cm(H).**
- (2) 重量: 42 kg.
■ **Weight: 42 kg.**
- (3) 使用电压: 110/220V 50/60Hz.
■ **Working voltage: 110/220V;50/60Hz**
- (4) 使用气压: 6 kg/cm².
■ **Working air pressure: 6 kg/cm².**
- (5) 锡球规格: 依 BGA 不同使用锡球规格而异.
■ **Solder ball specification: According to the solder ball spec being used by different kinds of BGA package.**
- (6) BGA 模具: 依 BGA 不同规格 SIZE 可更换需求 BGA 模具.
■ **BGA IC holder: It is available for changing-over different types of BGA IC holders according to different size or spec of BGA package.**
- (7) BGA 模具: 依 BGA 不同规格 SIZE 可更换需求锡球模具模具.
■ **Solder ball screening fixture: It is available for changing-over different ball screening fixtures according to different size or spec of solder ball.**
- (7) 锡球植入速度: 锡球植入 BGA-PAD 点可微调控制锡球植入速度.
■ **Solder ball placing speed: The speed for placing solder balls onto BGA pads can be adjusted and fine-tuning controlled.**
- (8) 锡球植入率: 百分之百.
■ **Ball-placing yield rate: 100%.**
- (9) 锡球植入精度: 0.03 mm.
■ **Ball-placing accuracy: 0.03mm.**
- (10) 模具槽退料: 退料速度 30 - 300 mm/S.
■ **BGA IC holder unloading speed: Unloading speed 30~300 mm/s.**
- (11) 自动移印植球时间: 42/sec
■ **Automatic ball-placing operation cycle time : 42 seconds.**

锡球植入机,未拆下 BGA 重新植入全新锡球,以利重新回焊维修,本设备提供 SMT 业界进入 BGA 作业技术层次的提升,本机为 BGA 生产作业得力助手。The solder ball placement system places new solder balls again onto ball removed BGA-IC for new reflowing rework. This equipment provides a technology promotion for traditional BGA operation in SMT industry. It is a very useful tool for BGA production.

本设备荣获多国专利仿冒必究

[There are patents approved by lots of countries for this equipment. All rights are reserved]

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